

ABSTRACT

A semiconductor die is formed in a process that forms a hole through the wafer prior to the formation of the contacts and the metal-1
5 layer of an interconnect structure. The through-the-wafer hole is formed by using a wafer with a $\langle 110 \rangle$ crystallographic orientation and a wet etch, such as with ethanol (KOH) or tetramethylammonium hydroxide (TMAH).

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